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Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
Data Converters	A/D 4x8b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	18-DIP (0.300", 7.62mm)
Supplier Device Package	18-PDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c715-04i-p

1.0 GENERAL DESCRIPTION

The PIC16C71X is a family of low-cost, high-performance, CMOS, fully-static, 8-bit microcontrollers with integrated analog-to-digital (A/D) converters, in the PIC16CXX mid-range family.

All PIC16/17 microcontrollers employ an advanced RISC architecture. The PIC16CXX microcontroller family has enhanced core features, eight-level deep stack, and multiple internal and external interrupt sources. The separate instruction and data buses of the Harvard architecture allow a 14-bit wide instruction word with the separate 8-bit wide data. The two stage instruction pipeline allows all instructions to execute in a single cycle, except for program branches which require two cycles. A total of 35 instructions (reduced instruction set) are available. Additionally, a large register set gives some of the architectural innovations used to achieve a very high performance.

PIC16CXX microcontrollers typically achieve a 2:1 code compression and a 4:1 speed improvement over other 8-bit microcontrollers in their class.

The **PIC16C710/71** devices have 36 bytes of RAM, the **PIC16C711** has 68 bytes of RAM and the **PIC16C715** has 128 bytes of RAM. Each device has 13 I/O pins. In addition a timer/counter is available. Also a 4-channel high-speed 8-bit A/D is provided. The 8-bit resolution is ideally suited for applications requiring low-cost analog interface, e.g. thermostat control, pressure sensing, etc.

The PIC16C71X family has special features to reduce external components, thus reducing cost, enhancing system reliability and reducing power consumption. There are four oscillator options, of which the single pin RC oscillator provides a low-cost solution, the LP oscillator minimizes power consumption, XT is a standard crystal, and the HS is for High Speed crystals. The SLEEP (power-down) feature provides a power saving mode. The user can wake up the chip from SLEEP through several external and internal interrupts and resets.

A highly reliable Watchdog Timer with its own on-chip RC oscillator provides protection against software lock-up.

A UV erasable Cerdip packaged version is ideal for code development while the cost-effective One-Time-Programmable (OTP) version is suitable for production in any volume.

The PIC16C71X family fits perfectly in applications ranging from security and remote sensors to appliance control and automotive. The EPROM technology makes customization of application programs (transmitter codes, motor speeds, receiver frequencies, etc.) extremely fast and convenient. The small footprint packages make this microcontroller series perfect for all applications with space limitations. Low cost, low power, high performance, ease of use and I/O flexibility make the PIC16C71X very versatile even in areas where no microcontroller use has been considered before (e.g. timer functions, serial communication, capture and compare, PWM functions and coprocessor applications).

1.1 Family and Upward Compatibility

Users familiar with the PIC16C5X microcontroller family will realize that this is an enhanced version of the PIC16C5X architecture. Please refer to Appendix A for a detailed list of enhancements. Code written for the PIC16C5X can be easily ported to the PIC16CXX family of devices (Appendix B).

1.2 Development Support

PIC16C71X devices are supported by the complete line of Microchip Development tools.

Please refer to Section 10.0 for more details about Microchip's development tools.

3.0 ARCHITECTURAL OVERVIEW

The high performance of the PIC16CXX family can be attributed to a number of architectural features commonly found in RISC microprocessors. To begin with, the PIC16CXX uses a Harvard architecture, in which, program and data are accessed from separate memories using separate buses. This improves bandwidth over traditional von Neumann architecture in which program and data are fetched from the same memory using the same bus. Separating program and data buses further allows instructions to be sized differently than the 8-bit wide data word. Instruction opcodes are 14-bits wide making it possible to have all single word instructions. A 14-bit wide program memory access bus fetches a 14-bit instruction in a single cycle. A two-stage pipeline overlaps fetch and execution of instructions (Example 3-1). Consequently, all instructions (35) execute in a single cycle (200 ns @ 20 MHz) except for program branches.

The table below lists program memory (EPROM) and data memory (RAM) for each PIC16C71X device.

Device	Program Memory	Data Memory
PIC16C710	512 x 14	36 x 8
PIC16C71	1K x 14	36 x 8
PIC16C711	1K x 14	68 x 8
PIC16C715	2K x 14	128 x 8

The PIC16CXX can directly or indirectly address its register files or data memory. All special function registers, including the program counter, are mapped in the data memory. The PIC16CXX has an orthogonal (symmetrical) instruction set that makes it possible to carry out any operation on any register using any addressing mode. This symmetrical nature and lack of 'special optimal situations' make programming with the PIC16CXX simple yet efficient. In addition, the learning curve is reduced significantly.

PIC16CXX devices contain an 8-bit ALU and working register. The ALU is a general purpose arithmetic unit. It performs arithmetic and Boolean functions between the data in the working register and any register file.

The ALU is 8-bits wide and capable of addition, subtraction, shift and logical operations. Unless otherwise mentioned, arithmetic operations are two's complement in nature. In two-operand instructions, typically one operand is the working register (W register). The other operand is a file register or an immediate constant. In single operand instructions, the operand is either the W register or a file register.

The W register is an 8-bit working register used for ALU operations. It is not an addressable register.

Depending on the instruction executed, the ALU may affect the values of the Carry (C), Digit Carry (DC), and Zero (Z) bits in the STATUS register. The C and DC bits operate as a borrow bit and a digit borrow out bit, respectively, in subtraction. See the `SUBLW` and `SUBWF` instructions for examples.

5.2 PORTB and TRISB Registers

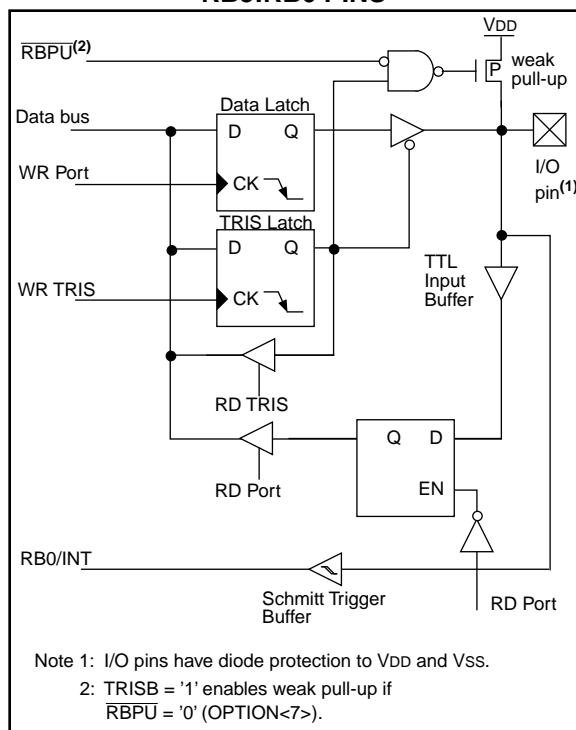
PORTB is an 8-bit wide bi-directional port. The corresponding data direction register is TRISB. Setting a bit in the TRISB register puts the corresponding output driver in a hi-impedance input mode. Clearing a bit in the TRISB register puts the contents of the output latch on the selected pin(s).

EXAMPLE 5-2: INITIALIZING PORTB

```
BCF    STATUS, RP0 ;
CLRF   PORTB       ; Initialize PORTB by
                   ; clearing output
                   ; data latches
BSF     STATUS, RP0 ; Select Bank 1
MOVLW  0xCF        ; Value used to
                   ; initialize data
                   ; direction
MOVWF   TRISB       ; Set RB<3:0> as inputs
                   ; RB<5:4> as outputs
                   ; RB<7:6> as inputs
```

Each of the PORTB pins has a weak internal pull-up. A single control bit can turn on all the pull-ups. This is performed by clearing bit $\overline{\text{RBP}}\text{U}$ (OPTION<7>). The weak pull-up is automatically turned off when the port pin is configured as an output. The pull-ups are disabled on a Power-on Reset.

FIGURE 5-3: BLOCK DIAGRAM OF RB3:RB0 PINS



Four of PORTB's pins, RB7:RB4, have an interrupt on change feature. Only pins configured as inputs can cause this interrupt to occur (i.e. any RB7:RB4 pin configured as an output is excluded from the interrupt on change comparison). The input pins (of RB7:RB4) are compared with the old value latched on the last read of PORTB. The "mismatch" outputs of RB7:RB4 are OR'ed together to generate the RB Port Change Interrupt with flag bit RBIF (INTCON<0>).

This interrupt can wake the device from SLEEP. The user, in the interrupt service routine, can clear the interrupt in the following manner:

- Any read or write of PORTB. This will end the mismatch condition.
- Clear flag bit RBIF.

A mismatch condition will continue to set flag bit RBIF. Reading PORTB will end the mismatch condition, and allow flag bit RBIF to be cleared.

This interrupt on mismatch feature, together with software configurable pull-ups on these four pins allow easy interface to a keypad and make it possible for wake-up on key-depression. Refer to the Embedded Control Handbook, "Implementing Wake-Up on Key Stroke" (AN552).

Note: For the PIC16C71 if a change on the I/O pin should occur when the read operation is being executed (start of the Q2 cycle), then interrupt flag bit RBIF may not get set.

The interrupt on change feature is recommended for wake-up on key depression operation and operations where PORTB is only used for the interrupt on change feature. Polling of PORTB is not recommended while using the interrupt on change feature.

6.2 Using Timer0 with an External Clock

When an external clock input is used for Timer0, it must meet certain requirements. The requirements ensure the external clock can be synchronized with the internal phase clock (TOSC). Also, there is a delay in the actual incrementing of Timer0 after synchronization.

6.2.1 EXTERNAL CLOCK SYNCHRONIZATION

When no prescaler is used, the external clock input is the same as the prescaler output. The synchronization of T0CKI with the internal phase clocks is accomplished by sampling the prescaler output on the Q2 and Q4 cycles of the internal phase clocks (Figure 6-5). Therefore, it is necessary for T0CKI to be high for at least 2TOSC (and a small RC delay of 20 ns) and low for at least 2TOSC (and a small RC delay of 20 ns). Refer to the electrical specification of the desired device.

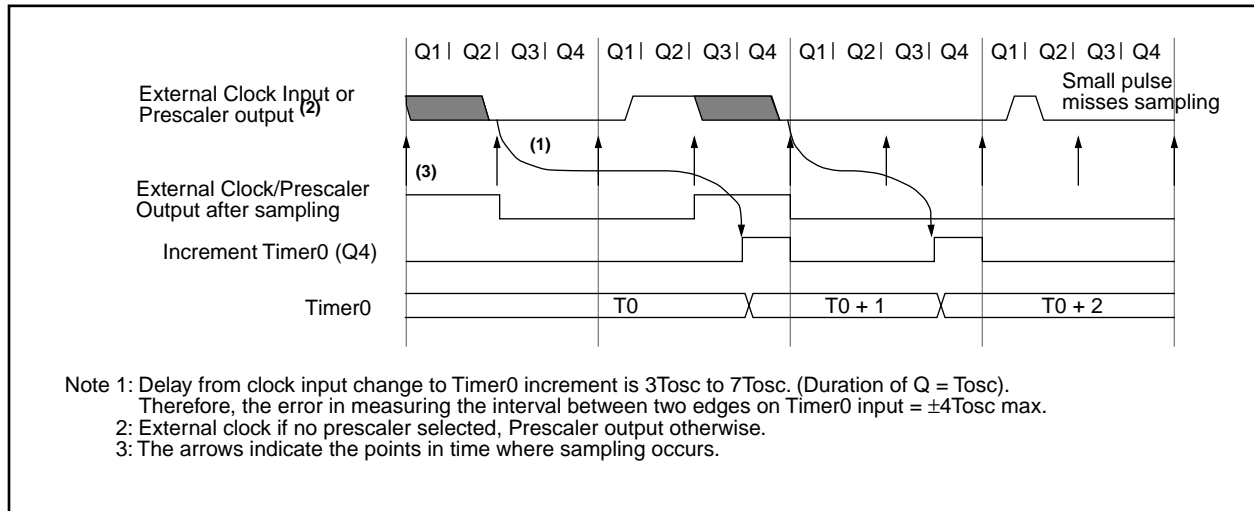
When a prescaler is used, the external clock input is divided by the asynchronous ripple-counter type pres-

caler so that the prescaler output is symmetrical. For the external clock to meet the sampling requirement, the ripple-counter must be taken into account. Therefore, it is necessary for T0CKI to have a period of at least 4TOSC (and a small RC delay of 40 ns) divided by the prescaler value. The only requirement on T0CKI high and low time is that they do not violate the minimum pulse width requirement of 10 ns. Refer to parameters 40, 41 and 42 in the electrical specification of the desired device.

6.2.2 TMR0 INCREMENT DELAY

Since the prescaler output is synchronized with the internal clocks, there is a small delay from the time the external clock edge occurs to the time the Timer0 module is actually incremented. Figure 6-5 shows the delay from the external clock edge to the timer incrementing.

FIGURE 6-5: TIMER0 TIMING WITH EXTERNAL CLOCK



7.4.1 FASTER CONVERSION - LOWER RESOLUTION TRADE-OFF

Not all applications require a result with 8-bits of resolution, but may instead require a faster conversion time. The A/D module allows users to make the trade-off of conversion speed to resolution. Regardless of the resolution required, the acquisition time is the same. To speed up the conversion, the clock source of the A/D module may be switched so that the TAD time violates the minimum specified time (see the applicable electrical specification). Once the TAD time violates the minimum specified time, all the following A/D result bits are not valid (see A/D Conversion Timing in the Electrical Specifications section.) The clock sources may only be switched between the three oscillator versions (cannot be switched from/to RC). The equation to determine the time before the oscillator can be switched is as follows:

$$\text{Conversion time} = 2T_{AD} + N \cdot T_{AD} + (8 - N)(2T_{OSC})$$

Where: N = number of bits of resolution required.

Since the TAD is based from the device oscillator, the user must use some method (a timer, software loop, etc.) to determine when the A/D oscillator may be changed. Example 7-3 shows a comparison of time required for a conversion with 4-bits of resolution, versus the 8-bit resolution conversion. The example is for devices operating at 20 MHz and 16 MHz (The A/D clock is programmed for 32TOSC), and assumes that immediately after 6TAD, the A/D clock is programmed for 2TOSC.

The 2TOSC violates the minimum TAD time since the last 4-bits will not be converted to correct values.

EXAMPLE 7-3: 4-BIT vs. 8-BIT CONVERSION TIMES

	Freq. (MHz) ⁽¹⁾	Resolution	
		4-bit	8-bit
TAD	20	1.6 μ s	1.6 μ s
	16	2.0 μ s	2.0 μ s
TOSC	20	50 ns	50 ns
	16	62.5 ns	62.5 ns
$2T_{AD} + N \cdot T_{AD} + (8 - N)(2T_{OSC})$	20	10 μ s	16 μ s
	16	12.5 μ s	20 μ s

Note 1: The PIC16C71 has a minimum TAD time of 2.0 μ s.
All other PIC16C71X devices have a minimum TAD time of 1.6 μ s.

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FIGURE 8-2: CONFIGURATION WORD, PIC16C710/711

CP0	CP0	CP0	CP0	CP0	CP0	CP0	BODEN	CP0	CP0	PWRT $\overline{\text{E}}$	WDTE	FOSC1	FOSC0	Register: CONFIG Address 2007h
bit13										bit0				
bit 13-7 CP0 : Code protection bits ⁽²⁾														
5-4: 1 = Code protection off														
0 = All memory is code protected, but 00h - 3Fh is writable														
bit 6: BODEN : Brown-out Reset Enable bit ⁽¹⁾														
1 = BOR enabled														
0 = BOR disabled														
bit 3: PWRT$\overline{\text{E}}$: Power-up Timer Enable bit ⁽¹⁾														
1 = PWRT disabled														
0 = PWRT enabled														
bit 2: WDTE : Watchdog Timer Enable bit														
1 = WDT enabled														
0 = WDT disabled														
bit 1-0: FOSC1:FOSC0 : Oscillator Selection bits														
11 = RC oscillator														
10 = HS oscillator														
01 = XT oscillator														
00 = LP oscillator														
Note 1: Enabling Brown-out Reset automatically enables Power-up Timer (PWRT) regardless of the value of bit PWRT$\overline{\text{E}}$. Ensure the Power-up Timer is enabled anytime Brown-out Reset is enabled.														
2: All of the CP0 bits have to be given the same value to enable the code protection scheme listed.														

FIGURE 8-3: CONFIGURATION WORD, PIC16C715

CP1	CP0	CP1	CP0	CP1	CP0	MPEEN	BODEN	CP1	CP0	PWRT $\overline{\text{E}}$	WDTE	FOSC1	FOSC0	Register: CONFIG Address 2007h
-----	-----	-----	-----	-----	-----	-------	-------	-----	-----	----------------------------	------	-------	-------	-----------------------------------

bit13

bit0

bit 13-8 **CP1:CP0:** Code Protection bits ⁽²⁾

5-4: 11 = Code protection off
10 = Upper half of program memory code protected
01 = Upper 3/4th of program memory code protected
00 = All memory is code protected

bit 7: **MPEEN:** Memory Parity Error Enable
1 = Memory Parity Checking is enabled
0 = Memory Parity Checking is disabled

bit 6: **BODEN:** Brown-out Reset Enable bit ⁽¹⁾
1 = BOR enabled
0 = BOR disabled

bit 3: **PWRT $\overline{\text{E}}$:** Power-up Timer Enable bit ⁽¹⁾
1 = PWRT disabled
0 = PWRT enabled

bit 2: **WDTE:** Watchdog Timer Enable bit
1 = WDT enabled
0 = WDT disabled

bit 1-0: **FOSC1:FOSC0:** Oscillator Selection bits
11 = RC oscillator
10 = HS oscillator
01 = XT oscillator
00 = LP oscillator

Note 1: Enabling Brown-out Reset automatically enables Power-up Timer (PWRT) regardless of the value of bit **PWRT $\overline{\text{E}}$** . Ensure the Power-up Timer is enabled anytime Brown-out Reset is enabled.

2: All of the CP1:CP0 pairs have to be given the same value to enable the code protection scheme listed.

8.5 Interrupts

Applicable Devices	710	71	711	715
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The PIC16C71X family has 4 sources of interrupt.

Interrupt Sources
External interrupt RB0/INT
TMR0 overflow interrupt
PORTB change interrupts (pins RB7:RB4)
A/D Interrupt

The interrupt control register (INTCON) records individual interrupt requests in flag bits. It also has individual and global interrupt enable bits.

Note: Individual interrupt flag bits are set regardless of the status of their corresponding mask bit or the GIE bit.

A global interrupt enable bit, GIE (INTCON<7>) enables (if set) all un-masked interrupts or disables (if cleared) all interrupts. When bit GIE is enabled, and an interrupt's flag bit and mask bit are set, the interrupt will vector immediately. Individual interrupts can be disabled through their corresponding enable bits in various registers. Individual interrupt bits are set regardless of the status of the GIE bit. The GIE bit is cleared on reset.

The "return from interrupt" instruction, RETFIE, exits the interrupt routine as well as sets the GIE bit, which re-enables interrupts.

The RB0/INT pin interrupt, the RB port change interrupt and the TMR0 overflow interrupt flags are contained in the INTCON register.

The peripheral interrupt flags are contained in the special function registers PIR1 and PIR2. The corresponding interrupt enable bits are contained in special function registers PIE1 and PIE2, and the peripheral interrupt enable bit is contained in special function register INTCON.

When an interrupt is responded to, the GIE bit is cleared to disable any further interrupt, the return address is pushed onto the stack and the PC is loaded with 0004h. Once in the interrupt service routine the source(s) of the interrupt can be determined by polling the interrupt flag bits. The interrupt flag bit(s) must be cleared in software before re-enabling interrupts to avoid recursive interrupts.

For external interrupt events, such as the INT pin or PORTB change interrupt, the interrupt latency will be three or four instruction cycles. The exact latency depends when the interrupt event occurs (Figure 8-19). The latency is the same for one or two cycle instructions. Individual interrupt flag bits are set regardless of the status of their corresponding mask bit or the GIE bit.

Note: For the PIC16C71
If an interrupt occurs while the Global Interrupt Enable (GIE) bit is being cleared, the GIE bit may unintentionally be re-enabled by the user's Interrupt Service Routine (the RETFIE instruction). The events that would cause this to occur are:

1. An instruction clears the GIE bit while an interrupt is acknowledged.
2. The program branches to the Interrupt vector and executes the Interrupt Service Routine.
3. The Interrupt Service Routine completes with the execution of the RETFIE instruction. This causes the GIE bit to be set (enables interrupts), and the program returns to the instruction after the one which was meant to disable interrupts.

Perform the following to ensure that interrupts are globally disabled:

```

LOOP BCF    INTCON, GIE    ; Disable global
                               ; interrupt bit
      BTFSC INTCON, GIE    ; Global interrupt
                               ; disabled?
      GOTO  LOOP           ; NO, try again
      :                   ; Yes, continue
                               ; with program
                               ; flow

```


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NOTES:

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TABLE 9-2: PIC16CXX INSTRUCTION SET

Mnemonic, Operands	Description	Cycles	14-Bit Opcode				Status Affected	Notes	
			MSb		LSb				
BYTE-ORIENTED FILE REGISTER OPERATIONS									
ADDWF	f, d	Add W and f	1	00	0111	dfff	ffff	C,DC,Z	1,2
ANDWF	f, d	AND W with f	1	00	0101	dfff	ffff	Z	1,2
CLRF	f	Clear f	1	00	0001	1fff	ffff	Z	2
CLRW	-	Clear W	1	00	0001	0xxx	xxxx	Z	
COMF	f, d	Complement f	1	00	1001	dfff	ffff	Z	1,2
DECF	f, d	Decrement f	1	00	0011	dfff	ffff	Z	1,2
DECFSZ	f, d	Decrement f, Skip if 0	1(2)	00	1011	dfff	ffff		1,2,3
INCF	f, d	Increment f	1	00	1010	dfff	ffff	Z	1,2
INCFSZ	f, d	Increment f, Skip if 0	1(2)	00	1111	dfff	ffff		1,2,3
IORWF	f, d	Inclusive OR W with f	1	00	0100	dfff	ffff	Z	1,2
MOVF	f, d	Move f	1	00	1000	dfff	ffff	Z	1,2
MOVWF	f	Move W to f	1	00	0000	1fff	ffff		
NOP	-	No Operation	1	00	0000	0xx0	0000		
RLF	f, d	Rotate Left f through Carry	1	00	1101	dfff	ffff	C	1,2
RRF	f, d	Rotate Right f through Carry	1	00	1100	dfff	ffff	C	1,2
SUBWF	f, d	Subtract W from f	1	00	0010	dfff	ffff	C,DC,Z	1,2
SWAPF	f, d	Swap nibbles in f	1	00	1110	dfff	ffff		1,2
XORWF	f, d	Exclusive OR W with f	1	00	0110	dfff	ffff	Z	1,2
BIT-ORIENTED FILE REGISTER OPERATIONS									
BCF	f, b	Bit Clear f	1	01	00bb	bfff	ffff		1,2
BSF	f, b	Bit Set f	1	01	01bb	bfff	ffff		1,2
BTFSC	f, b	Bit Test f, Skip if Clear	1 (2)	01	10bb	bfff	ffff		3
BTFSS	f, b	Bit Test f, Skip if Set	1 (2)	01	11bb	bfff	ffff		3
LITERAL AND CONTROL OPERATIONS									
ADDLW	k	Add literal and W	1	11	111x	kkkk	kkkk	C,DC,Z	
ANDLW	k	AND literal with W	1	11	1001	kkkk	kkkk	Z	
CALL	k	Call subroutine	2	10	0kkk	kkkk	kkkk		
CLRWDT	-	Clear Watchdog Timer	1	00	0000	0110	0100	TO,PD	
GOTO	k	Go to address	2	10	1kkk	kkkk	kkkk		
IORLW	k	Inclusive OR literal with W	1	11	1000	kkkk	kkkk	Z	
MOVLW	k	Move literal to W	1	11	00xx	kkkk	kkkk		
RETFIE	-	Return from interrupt	2	00	0000	0000	1001		
RETLW	k	Return with literal in W	2	11	01xx	kkkk	kkkk		
RETURN	-	Return from Subroutine	2	00	0000	0000	1000		
SLEEP	-	Go into standby mode	1	00	0000	0110	0011	TO,PD	
SUBLW	k	Subtract W from literal	1	11	110x	kkkk	kkkk	C,DC,Z	
XORLW	k	Exclusive OR literal with W	1	11	1010	kkkk	kkkk	Z	

- Note 1: When an I/O register is modified as a function of itself (e.g., `MOVF PORTB, 1`), the value used will be that value present on the pins themselves. For example, if the data latch is '1' for a pin configured as input and is driven low by an external device, the data will be written back with a '0'.
- 2: If this instruction is executed on the TMR0 register (and, where applicable, d = 1), the prescaler will be cleared if assigned to the Timer0 Module.
- 3: If Program Counter (PC) is modified or a conditional test is true, the instruction requires two cycles. The second cycle is executed as a NOP.

BTFSS		Bit Test f, Skip if Set						
Syntax:	[label] BTFSS f,b							
Operands:	0 ≤ f ≤ 127 0 ≤ b < 7							
Operation:	skip if (f<b) = 1							
Status Affected:	None							
Encoding:	<table><tr><td>01</td><td>11bb</td><td>bfff</td><td>ffff</td></tr></table>				01	11bb	bfff	ffff
01	11bb	bfff	ffff					
Description:	If bit 'b' in register 'f' is '0' then the next instruction is executed. If bit 'b' is '1', then the next instruction is discarded and a NOP is executed instead, making this a 2TCY instruction.							
Words:	1							
Cycles:	1(2)							
Q Cycle Activity:	Q1	Q2	Q3	Q4				
	Decode	Read register 'f'	Process data	NOP				
If Skip:	(2nd Cycle)							
	Q1	Q2	Q3	Q4				
	NOP	NOP	NOP	NOP				

Example

```

HERE    BTFSC  FLAG,1
FALSE   GOTO   PROCESS_CODE
TRUE    •
        •
        •

```

Before Instruction
PC = address HERE

After Instruction
if FLAG<1> = 0,
PC = address FALSE
if FLAG<1> = 1,
PC = address TRUE

CALL

Call Subroutine

Syntax:

[label] CALL k

Operands:

$0 \leq k \leq 2047$

Operation:

$(PC)+1 \rightarrow TOS,$
 $k \rightarrow PC<10:0>,$
 $(PCLATH<4:3>) \rightarrow PC<12:11>$

Status Affected:

None

Encoding:

10	0kkk	kkkk	kkkk
----	------	------	------

Description:

Call Subroutine. First, return address (PC+1) is pushed onto the stack. The eleven bit immediate address is loaded into PC bits <10:0>. The upper bits of the PC are loaded from PCLATH. CALL is a two cycle instruction.

Words:

1

Cycles:

2

Q Cycle Activity:

	Q1	Q2	Q3	Q4
1st Cycle	Decode	Read literal 'k', Push PC to Stack	Process data	Write to PC
2nd Cycle	NOP	NOP	NOP	NOP

Example

```

HERE    CALL   THERE

```

Before Instruction
PC = Address HERE

After Instruction
PC = Address THERE
TOS = Address HERE+1

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SLEEP

Syntax: [*label*] SLEEP

Operands: None

Operation: 00h → WDT,
0 → WDT prescaler,
1 → \overline{TO} ,
0 → \overline{PD}

Status Affected: \overline{TO} , \overline{PD}

Encoding:

00	0000	0110	0011
----	------	------	------

Description: The power-down status bit, \overline{PD} is cleared. Time-out status bit, \overline{TO} is set. Watchdog Timer and its prescaler are cleared. The processor is put into SLEEP mode with the oscillator stopped. See Section 8.8 for more details.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	NOP	NOP	Go to Sleep

Example: SLEEP

SUBLW

Subtract W from Literal

Syntax: [*label*] SUBLW k

Operands: $0 \leq k \leq 255$

Operation: $k - (W) \rightarrow (W)$

Status Affected: C, DC, Z

Encoding:

11	110x	kkkk	kkkk
----	------	------	------

Description: The W register is subtracted (2's complement method) from the eight bit literal 'k'. The result is placed in the W register.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read literal 'k'	Process data	Write to W

Example 1: SUBLW 0x02

Before Instruction

W = 1
C = ?
Z = ?

After Instruction

W = 1
C = 1; result is positive
Z = 0

Example 2: Before Instruction

W = 2
C = ?
Z = ?

After Instruction

W = 0
C = 1; result is zero
Z = 1

Example 3: Before Instruction

W = 3
C = ?
Z = ?

After Instruction

W = 0xFF
C = 0; result is negative
Z = 0

11.2 DC Characteristics: PIC16LC710-04 (Commercial, Industrial, Extended) PIC16LC711-04 (Commercial, Industrial, Extended)

Standard Operating Conditions (unless otherwise stated)							
DC CHARACTERISTICS							
Operating temperature							
0°C ≤ TA ≤ +70°C (commercial)							
-40°C ≤ TA ≤ +85°C (industrial)							
-40°C ≤ TA ≤ +125°C (extended)							
Param No.	Characteristic	Sym	Min	Typ†	Max	Units	Conditions
D001	Supply Voltage						
	Commercial/Industrial	VDD	2.5	-	6.0	V	LP, XT, RC osc configuration (DC - 4 MHz)
	Extended	VDD	3.0	-	6.0	V	LP, XT, RC osc configuration (DC - 4 MHz)
D002*	RAM Data Retention Voltage (Note 1)	VDR	-	1.5	-	V	
D003	VDD start voltage to ensure internal Power-on Reset signal	VPOR	-	VSS	-	V	See section on Power-on Reset for details
D004*	VDD rise rate to ensure internal Power-on Reset signal	SVDD	0.05	-	-	V/ms	See section on Power-on Reset for details
D005	Brown-out Reset Voltage	BVDD	3.7	4.0	4.3	V	BODEN configuration bit is enabled
D010	Supply Current (Note 2)	IDD	-	2.0	3.8	mA	XT, RC osc configuration FOSC = 4 MHz, VDD = 3.0V (Note 4)
D010A			-	22.5	48	μA	LP osc configuration FOSC = 32 kHz, VDD = 3.0V, WDT disabled
D015	Brown-out Reset Current (Note 5)	ΔIBOR	-	300*	500	μA	BOR enabled VDD = 5.0V
D020	Power-down Current (Note 3)	IPD	-	7.5	30	μA	VDD = 3.0V, WDT enabled, -40°C to +85°C
D021			-	0.9	5	μA	VDD = 3.0V, WDT disabled, 0°C to +70°C
D021A			-	0.9	5	μA	VDD = 3.0V, WDT disabled, -40°C to +85°C
D021B			-	0.9	10	μA	VDD = 3.0V, WDT disabled, -40°C to +125°C
D023	Brown-out Reset Current (Note 5)	ΔIBOR	-	300*	500	μA	BOR enabled VDD = 5.0V

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD

MCLR = VDD; WDT enabled/disabled as specified.

3: The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula $I_r = VDD/2R_{ext}$ (mA) with Rext in kOhm.

5: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

11.5 Timing Diagrams and Specifications

FIGURE 11-2: EXTERNAL CLOCK TIMING

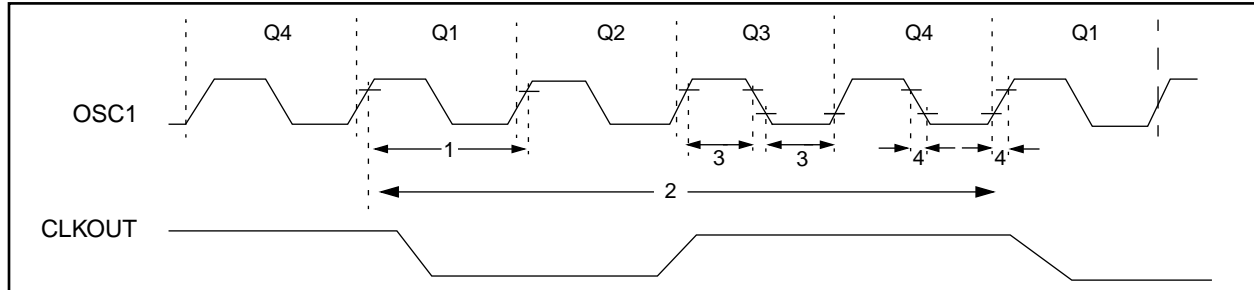


TABLE 11-2: EXTERNAL CLOCK TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
1	Fosc	External CLKIN Frequency (Note 1)	DC	—	4	MHz	XT osc mode
			DC	—	4	MHz	HS osc mode (-04)
			DC	—	10	MHz	HS osc mode (-10)
			DC	—	20	MHz	HS osc mode (-20)
			DC	—	200	kHz	LP osc mode
	Tosc	Oscillator Frequency (Note 1)	DC	—	4	MHz	RC osc mode
			0.1	—	4	MHz	XT osc mode
			4	—	20	MHz	HS osc mode
			5	—	200	kHz	LP osc mode
	Tosc	External CLKIN Period (Note 1)	250	—	—	ns	XT osc mode
			250	—	—	ns	HS osc mode (-04)
			100	—	—	ns	HS osc mode (-10)
			50	—	—	ns	HS osc mode (-20)
			5	—	—	μs	LP osc mode
		Oscillator Period (Note 1)	250	—	—	ns	RC osc mode
			250	—	10,000	ns	XT osc mode
			250	—	250	ns	HS osc mode (-04)
			100	—	250	ns	HS osc mode (-10)
			50	—	250	ns	HS osc mode (-20)
			5	—	—	μs	LP osc mode
2	Tcy	Instruction Cycle Time (Note 1)	200	—	DC	ns	Tcy = 4/Fosc
3	TosL, TosH	External Clock in (OSC1) High or Low Time	50	—	—	ns	XT oscillator
			2.5	—	—	μs	LP oscillator
			10	—	—	ns	HS oscillator
4	TosR, TosF	External Clock in (OSC1) Rise or Fall Time	—	—	25	ns	XT oscillator
			—	—	50	ns	LP oscillator
			—	—	15	ns	HS oscillator

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (Tcy) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices. OSC2 is disconnected (has no loading) for the PIC16C710/711.

PIC16C71X

Applicable Devices 710 71 711 715

FIGURE 11-3: CLKOUT AND I/O TIMING

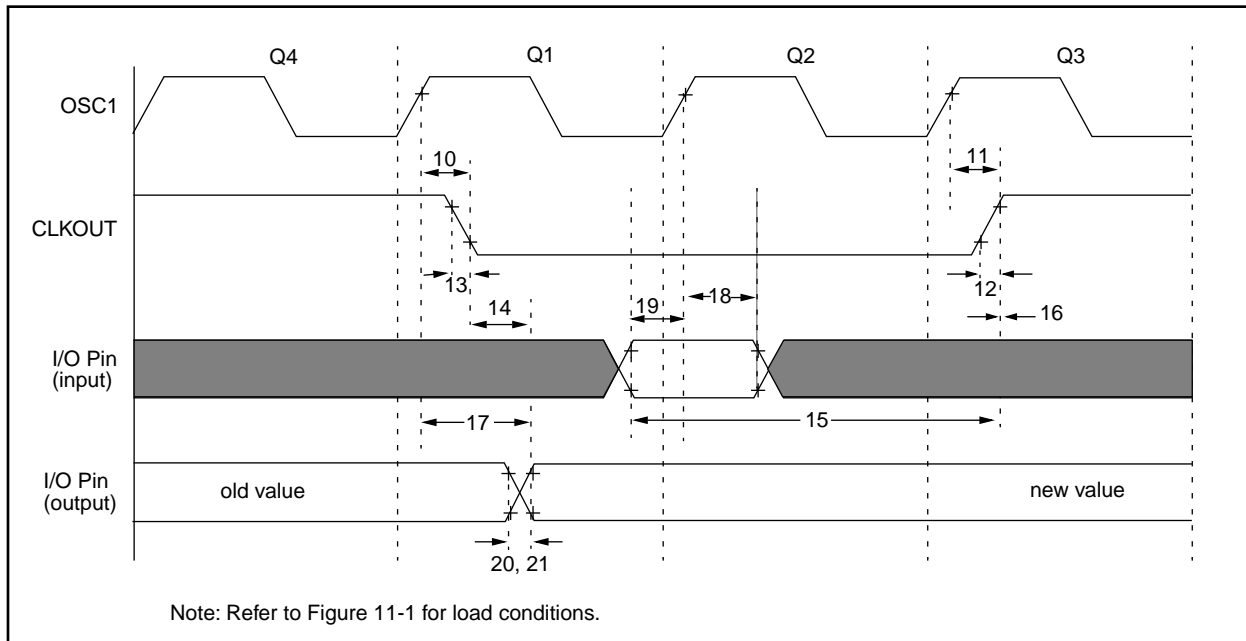


TABLE 11-3: CLKOUT AND I/O TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
10*	TosH2ckL	OSC1↑ to CLKOUT↓	—	15	30	ns	Note 1
11*	TosH2ckH	OSC1↑ to CLKOUT↑	—	15	30	ns	Note 1
12*	TckR	CLKOUT rise time	—	5	15	ns	Note 1
13*	TckF	CLKOUT fall time	—	5	15	ns	Note 1
14*	TckL2ioV	CLKOUT ↓ to Port out valid	—	—	0.5T _{CY} + 20	ns	Note 1
15*	TioV2ckH	Port in valid before CLKOUT ↑	0.25T _{CY} + 25	—	—	ns	Note 1
16*	TckH2iol	Port in hold after CLKOUT ↑	0	—	—	ns	Note 1
17*	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid	—	—	80 - 100	ns	
18*	TosH2iol	OSC1↑ (Q2 cycle) to Port input invalid (I/O in hold time)	TBD	—	—	ns	
19*	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)	TBD	—	—	ns	
20*	TioR	Port output rise time	PIC16C710/711	—	10	25	ns
			PIC16LC710/711	—	—	60	ns
21*	TioF	Port output fall time	PIC16C710/711	—	10	25	ns
			PIC16LC710/711	—	—	60	ns
22††*	Tinp	INT pin high or low time	20	—	—	ns	
23††*	Trbp	RB7:RB4 change INT high or low time	20	—	—	ns	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

†† These parameters are asynchronous events not related to any internal clock edges.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x T_{osc}.

Applicable Devices	710	71	711	715
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FIGURE 12-8: TYPICAL I_{PD} vs. V_{DD} BROWN-OUT DETECT ENABLED (RC MODE)

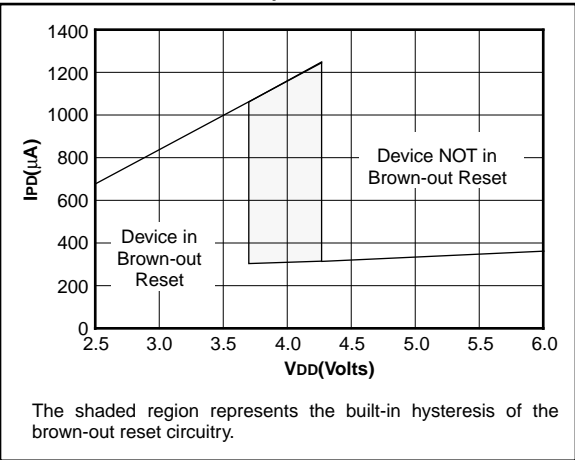


FIGURE 12-9: MAXIMUM I_{PD} vs. V_{DD} BROWN-OUT DETECT ENABLED (85°C TO -40°C, RC MODE)

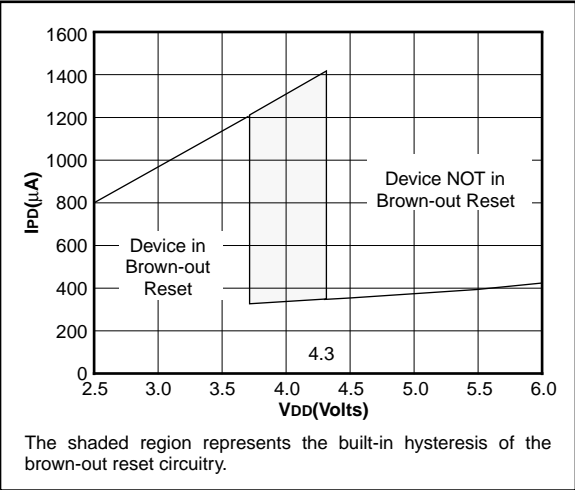


FIGURE 12-10: TYPICAL I_{PD} vs. TIMER1 ENABLED (32 kHz, RC0/RC1 = 33 pF/33 pF, RC MODE)

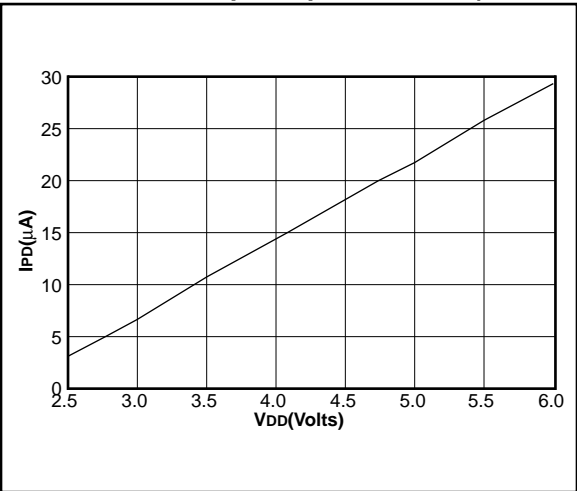
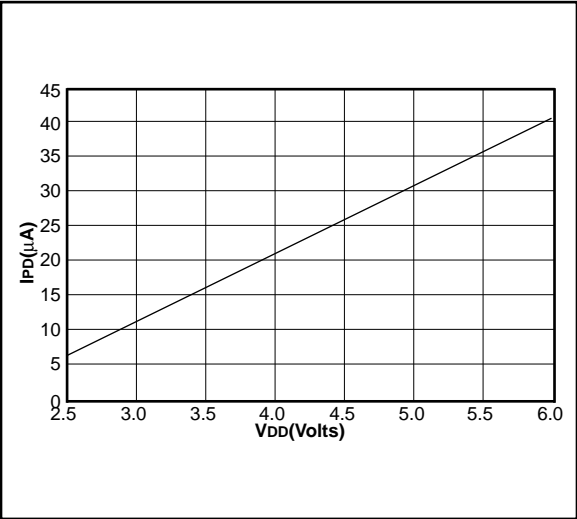


FIGURE 12-11: MAXIMUM I_{PD} vs. TIMER1 ENABLED (32 kHz, RC0/RC1 = 33 pF/33 pF, 85°C TO -40°C, RC MODE)



PIC16C71X

Applicable Devices

710	71	711	715
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FIGURE 14-16: TYPICAL I_{DD} vs. FREQUENCY (RC MODE @ 300 pF, 25°C)

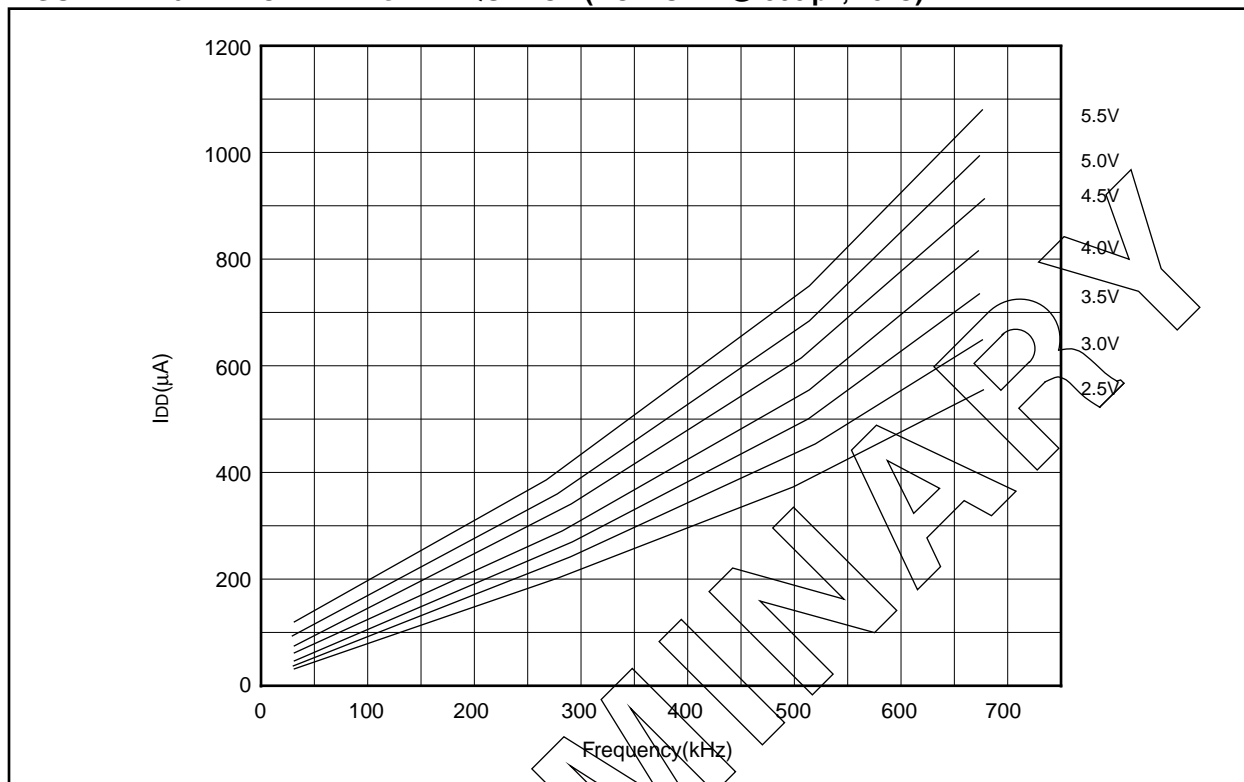
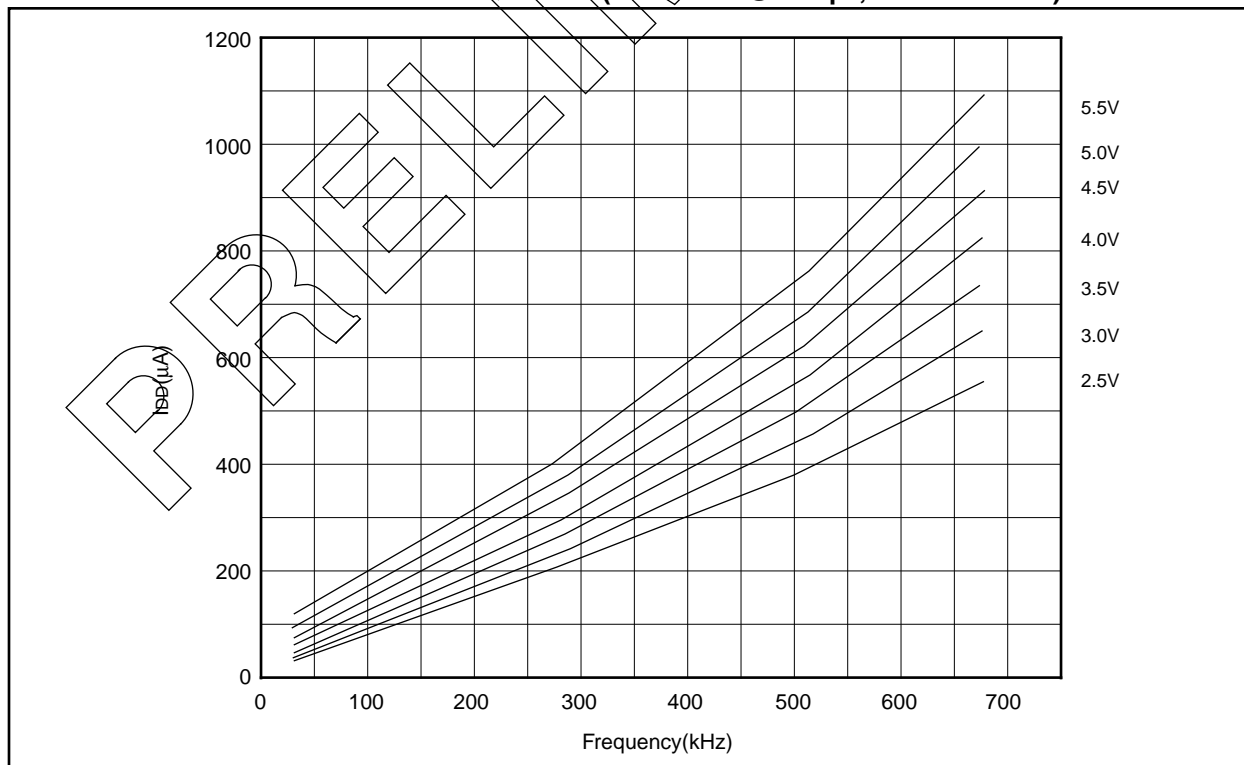


FIGURE 14-17: MAXIMUM I_{DD} vs. FREQUENCY (RC MODE @ 300 pF, -40°C TO 85°C)



PIC16C71X

Applicable Devices 710 71 711 715

FIGURE 15-3: CLKOUT AND I/O TIMING

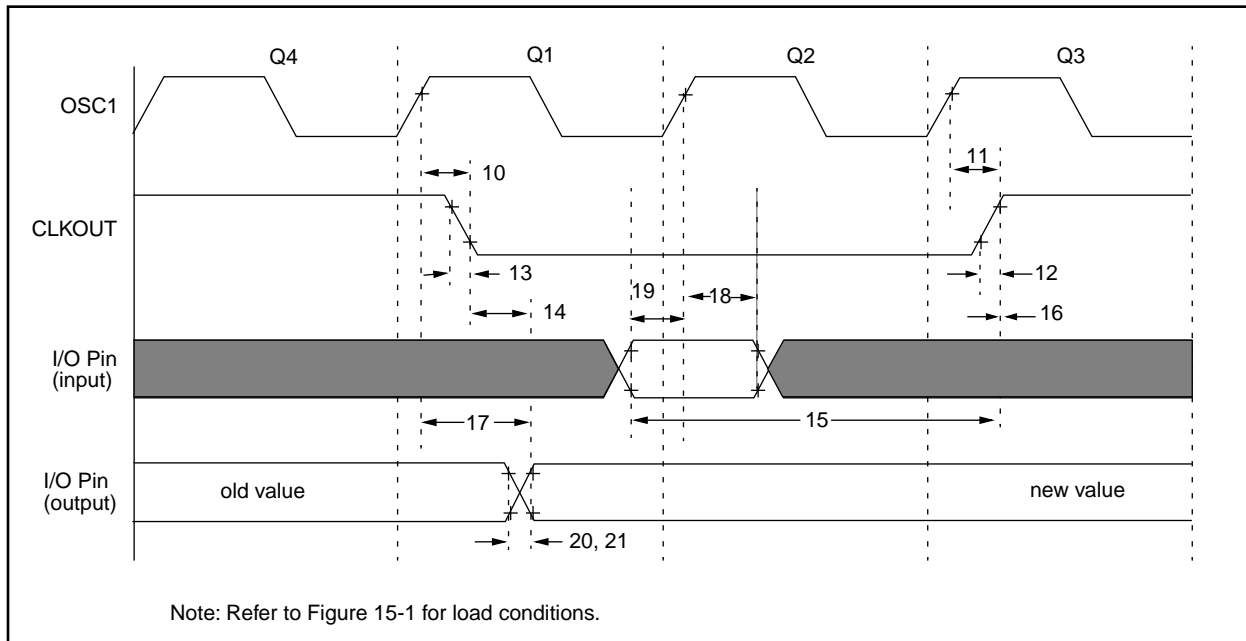


TABLE 15-3: CLKOUT AND I/O TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
10*	TosH2ckL	OSC1↑ to CLKOUT↓	—	15	30	ns	Note 1
11*	TosH2ckH	OSC1↑ to CLKOUT↑	—	15	30	ns	Note 1
12*	TckR	CLKOUT rise time	—	5	15	ns	Note 1
13*	TckF	CLKOUT fall time	—	5	15	ns	Note 1
14*	TckL2ioV	CLKOUT ↓ to Port out valid	—	—	0.5T _{CY} + 20	ns	Note 1
15*	TioV2ckH	Port in valid before CLKOUT ↑	0.25T _{CY} + 25	—	—	ns	Note 1
16*	TckH2ioL	Port in hold after CLKOUT ↑	0	—	—	ns	Note 1
17*	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid	—	—	80 - 100	ns	
18*	TosH2ioL	OSC1↑ (Q2 cycle) to Port input invalid (I/O in hold time)	PIC16C71	100	—	ns	
			PIC16LC71	200	—	ns	
19*	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)	0	—	—	ns	
20*	TioR	Port output rise time	PIC16C71	—	10	ns	
			PIC16LC71	—	—	60	ns
21*	TioF	Port output fall time	PIC16C71	—	10	ns	
			PIC16LC71	—	—	60	ns
22††*	Tinp	INT pin high or low time	20	—	—	ns	
23††*	Trbp	RB7:RB4 change INT high or low time	20	—	—	ns	

* These parameters are characterized but not tested.

†Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

†† These parameters are asynchronous events not related to any internal clock edges.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x T_{OSC}.

16.0 DC AND AC CHARACTERISTICS GRAPHS AND TABLES FOR PIC16C71

The graphs and tables provided in this section are for design guidance and are not tested or guaranteed. In some graphs or tables the data presented are outside specified operating range (e.g. outside specified V_{DD} range). This is for information only and devices are guaranteed to operate properly only within the specified range.

Note: The data presented in this section is a statistical summary of data collected on units from different lots over a period of time and matrix samples. 'Typical' represents the mean of the distribution while 'max' or 'min' represents (mean + 3σ) and (mean - 3σ) respectively where σ is standard deviation.

FIGURE 16-1: TYPICAL RC OSCILLATOR FREQUENCY vs. TEMPERATURE

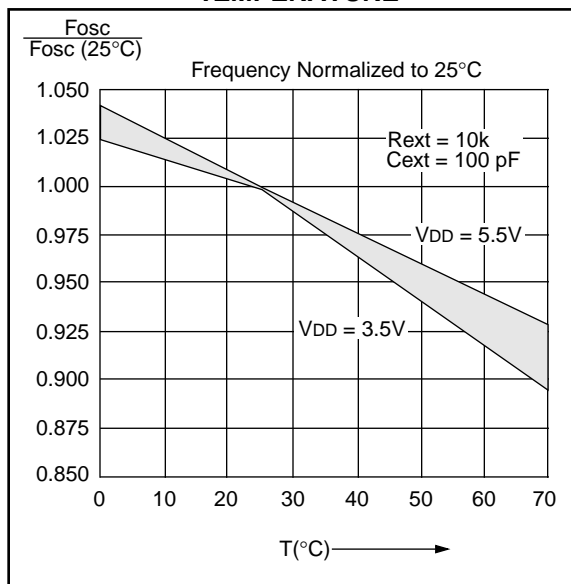


FIGURE 16-2: TYPICAL RC OSCILLATOR FREQUENCY vs. V_{DD}

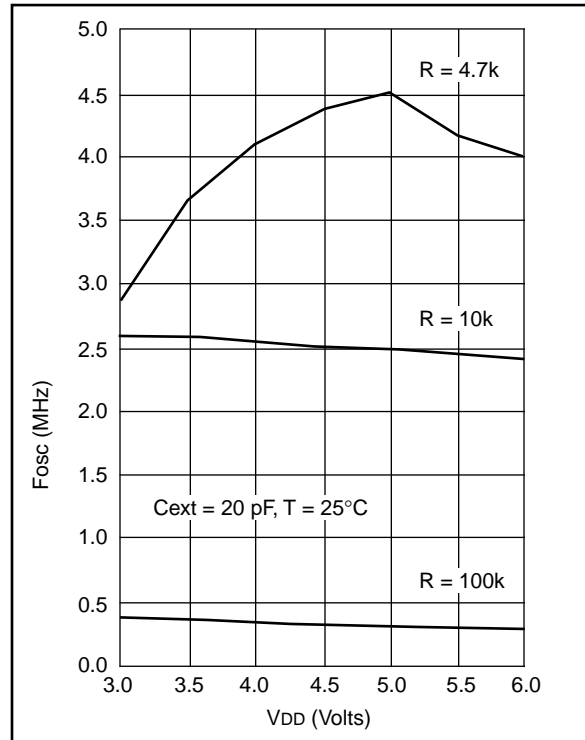
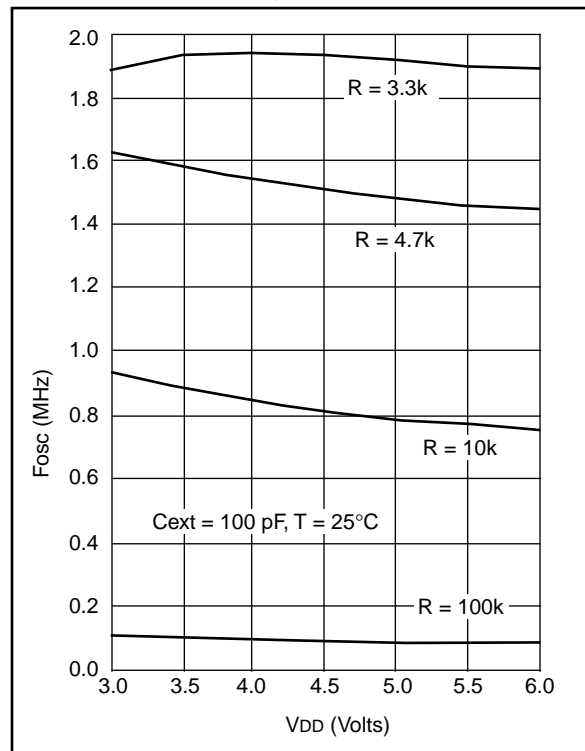


FIGURE 16-3: TYPICAL RC OSCILLATOR FREQUENCY vs. V_{DD}



NOTES:

Note the following details of the code protection feature on PICmicro® MCUs.

- The PICmicro family meets the specifications contained in the Microchip Data Sheet.
- Microchip believes that its family of PICmicro microcontrollers is one of the most secure products of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the PICmicro microcontroller in a manner outside the operating specifications contained in the data sheet. The person doing so may be engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as “unbreakable”.
- Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our product.

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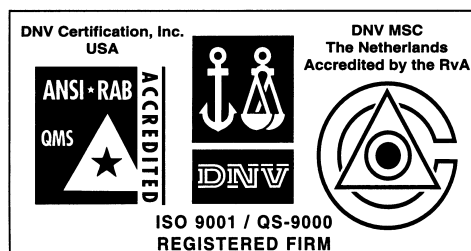
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